

Class	Subclass

ISSUE CLASSIFICATION

PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E.

PATENT DATE

SCANNED

Q-4

APPLICATION NO. 09/903070	CONT/PRIOR F	CLASS 053	SUBCLASS 449	ART UNIT 372 37240	EXAMINER KIAA Stashick
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APPLICANTS

374

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Methods of packaging semiconductor wafers by molding a packing bag about a carrying device that contains the semiconductor wafers

ISSUING CLASSIFICATION

ISSUING CLASSIFICATION									
ORIGINAL				CROSS REFERENCE(S)					
CLASS		SUBCLASS		CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)				
INTERNATIONAL CLASSIFICATION									

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	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
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<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____	_____ (Primary Examiner) (Date)			ISSUE FEE	
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